

PRODUCT GUIDE

Discrete IGBTs



SEMIGONDUGTOR

IGBT: Insulated Gate Bipolar Transistor

IGBTs combine the MOSFET advantage of high input impedance with the bipolar transistor advantage of high-voltage drive.

The conductivity modulation characteristics of a bipolar transistor make it ideal for load control applications that require high breakdown voltage and high current.

Toshiba offers a family of fast switching IGBTs, which are low in carrier injection and recombination in carrier.

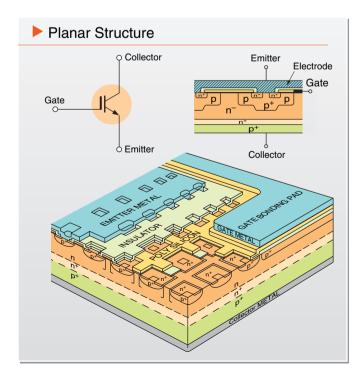
Features of the Toshiba Discrete IGBTs

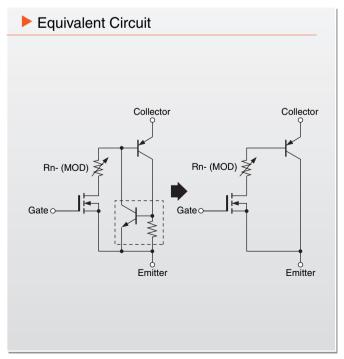
The Toshiba discrete IGBTs are available in high-voltage and high-current ratings. They are used in inverter and power conversion circuits for such diverse applications as motor drivers, uninterruptible power supply (UPS) systems, IH cookers, plasma display panels (PDPs), strobe flashes and so on.

- (1) IGBTs also featuring fast switching
- (2) Low collector-emitter saturation voltage even in the large current area
- (3) IGBTs featuring a built-in diode with optimal characteristics tailored to specific applications
- (4) High input impedance allows voltage drives
- (5) Available in a variety of packages

Construction

The basic structure of the planar IGBT consists of four layers (pnpn), as shown in the following figure. Low saturation voltage is achieved by using a pnp transistor to allow conductivity modulation during conduction. Unlike MOSFETs, the IGBT does not have an integral reverse diode, since the collector contact is made on the p⁺ layer.





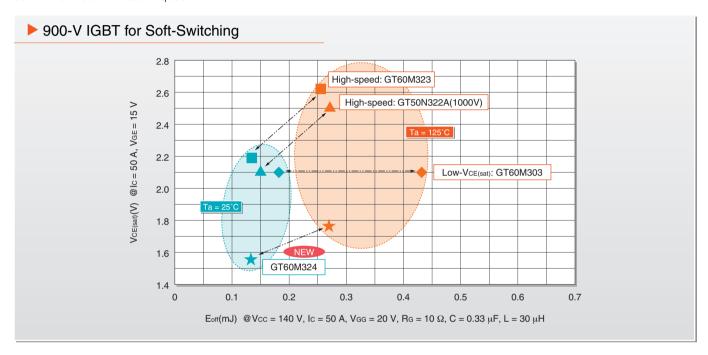
2 IGBT Technical Overview

Prior to the development of IGBTs, power MOSFETs were used for power amplifier applications which require high input impedance and fast switching. However, at high voltages, the on-state resistance rapidly increases as the breakdown voltage increases. It is thus difficult to improve the conduction loss of power MOSFETs.

On the other hand, the IGBT structure consists of a pnp bipolar transistor and a collector contact made on the p⁺ layer. The IGBT has a low on-state voltage drop due to conductivity modulation.

The following figure shows the VCE(sat) curve of a soft-switching 900-V IGBT. Toshiba has offered IGBTs featuring fast switching by using carrier lifetime control techniques. Now, Toshiba offers even faster IGBTs with optimized carrier injection into the collector p⁺ layer.

In the future, Toshiba will launch IGBTs with varied characteristics optimized for high-current-conduction and high-frequency-switching applications. The improvements in IGBTs will be spurred by optimized wafers, smaller pattern geometries and improved carrier lifetime control techniques.



Discrete IGBT Development Trends

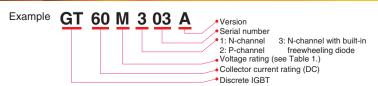
	(1) High ruggedness (3rd gen): Low VCE(sat) and high ruggedness d	e to optimized carrier injection and thinner wafers	
1200 V	(2) Soft switching (5th gen): Low VcE(sat) due to trench gate structure		
		(3) Soft switching (next gen): Thinner wafe process geometries	ers and fine
900 to	(1) Soft switching (4th gen): Low VCE(sat) due to trench gate structure		
1500 V	(2) Soft switching (5th gen): Low VcE(sat) due to optimized carrier in	ction and trench gate structure	
	(3)	Soft switching (6th gen): Thinner wafers and finer process geomet	ries
	(1) High ruggedness (3rd gen): Low VcE(sat) and high ruggedness d	e to optimized carrier injection and thinner wafers	
	(2) Fast switching (4th gen): High speedy tf due to optimized carrie	injection	
600 V		(4) Fast switching (next gen): T and finer process geometr	
	(3) Soft switching (4th gen): Low VcE(sat) due to trench gate structure		
	(5)	Soft switching (5th gen): Thinner wafers and finer process geomet	ries
	(1) Strobe flashes (5th gen): Low VcE(sat) due to trench gate structu		
400 V	(2) Strobe flashes (6th gen): High current due to trench gate structu	e and optimized wafers	
	(3) Strobe flashes (7th g	n): High current due to optimized wafers and finer process geometries	
300 to	(1) Plasma displays (4th gen): Low VcE(sat) due to trench gate struc	re and high IC due to lifetime control	
400 V	(2) Plasma displays (5th gen): Low	rurn-on loss due to finer process geometries	
.00 v	(3) Plasma displays (6	n gen): Low turn-on loss due to optimized wafers and finer process	s geometri
Year	2006 2008	2010 2012	

Discrete IGBT Product List

				TSON-8	TSSOP-8	SOP-8	TO-220NIS	TO-220SIS	TO-220SM	TO-3P(N)	TO-3P(N)IS	TO-3P(LH)
Applications and Features	Breakdown Voltage Vces (V) @Ta = 25°C	Rating @Ta	Current g Ic (A) = 25°C			m						
		DC	Pulse				OTF 1004		OTF 1044	111	111	111
		5 10	10 20				GT5J301 GT10J303		GT5J311 GT10J312	GT10J301		
		15	30				GT15J301		GT15J311			
General-purpose motors	600	20	40							GT20J301 GT20J101		
General-purpose inverters	000									GT30J301		
Hard switching		30	60							GT30J101		
fc: up to 20 kHz		50	100									GT50J301 GT50J102
High ruggedness		10	00							GT10Q301		G1300102
Series		10	20							GT10Q101		
	1200	15	30							GT15Q301 GT15Q102		
		25	50							GIIIGGIGE		GT25Q301
							07101001					GT25Q102
General-purpose inverters		10 15	20 30				GT10J321 GT15J321					
Fast switching		20	40				GT20J321					
Hard switching fc: up to 50 kHz	600	30	60							GT30J324	GT30J126	
										GT30J121		GT50J325
FS series		50	100									GT50J325
General-purpose inverters	600	15	30						GT15J331			
Low-Vce(sat) IGBT		30	100						G. 100001		GT30J322	
										GT40J321	G1300322	
		40	100							GT40J322		
		50	100							GT50J327		GT50J322
	600	50	120							GT50J328		GT50J322H
												GT60J321
Resonant switching		60	120									GT60J323
Soft switching		15	30								GT15M321	GT60J323H
Soft-Switching	900	50	120							GT50M322	GTTSWSZT	
Series	900	60	120							GT60M324		GT60M303
										GT50N322A		GT60M323
	1000	50	120							GT50N324		
	1000	57	120									GT60N322
	1200	60 42	120 80							GT40Q321		GT60N321
	1500	40	80							GT40G321		GT40T302
PFC	600	30	100								GT30J122	
			130	GT5G133	GT8G133							
Strobe flashes	400		150		GT8G133	GT8G132						
					GT8G136							
			200 120			GT10G131		GF30F122				
			120					GF30F122	GT45F131			
								GT30F124				
	300		200					GT45F122				
			200					GT45F123 GT45F124				
								GT45F125				
								GT45F127				
	330		200					GT30F125 GT45F128				
Plasma display panels			120					GT30G122				
parioio	400							GT45G122	GT45G131			
	400		200					GT45G123 GT45G124				
								GT45G125				
								GT30G123				
	430		200					GT30G124				
	430		200					GT30G125 GT45G127				
								GT45G128				
	600		200					GT30J124				

: New product

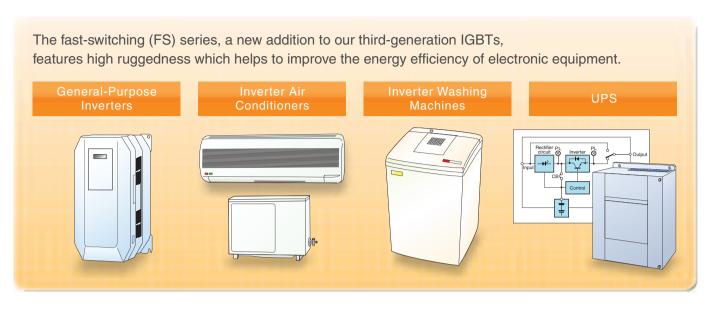
4 Part Numbering Scheme



etter	Voltage (V)	Letter	Voltage (V)	Letter	Voltage (V)
O	150	J	600	Q	1200
D	200	K	700	R	1300
Е	250	L	800	S	1400
Ŧ	300	M	900	Т	1500
G	400	Ν	1000	U	1600
H	500	Р	1100	V	1700
	C D E	C 150 D 200 E 250 F 300 G 400	C 150 J D 200 K E 250 L F 300 M G 400 N	C 150 J 600 D 200 K 700 E 250 L 800 F 300 M 900 G 400 N 1000	C 150 J 600 Q D 200 K 700 R E 250 L 800 S F 300 M 900 T G 400 N 1000 U

Table 1

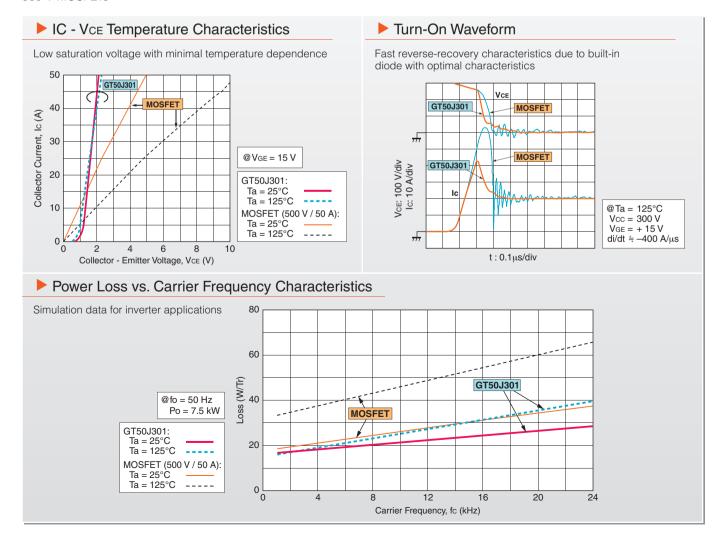
5-1 General-Purpose Inverter



Discrete IGBT Trend

For general-purpose inverters

Our 3rd generation low-loss and low-noise IGBTs are ideal for inverter applications to reduce switching loss and thus improve energy efficiency. The following graphs compare the thermal and turn-on characteristics of our 3rd generation IGBTs and 500-V MOSFETs

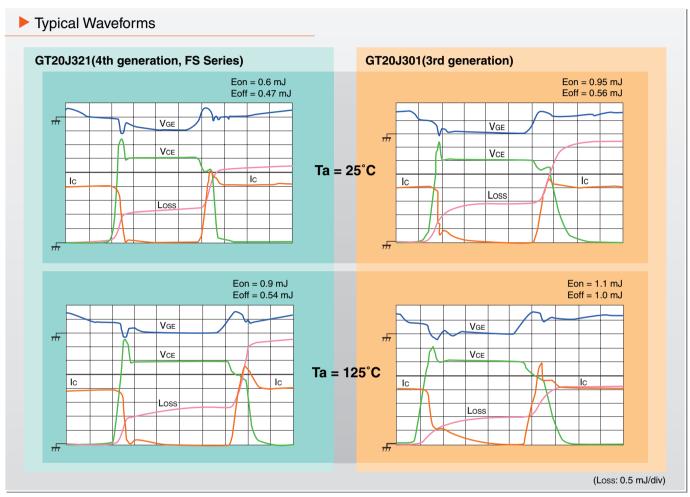


5-1 General-Purpose Inverter

Fast-Switching (FS) Series

► For general-purpose inverters

Compared to the third-generation highly rugged series, the FS series is optimized for switching speed, reducing the total switching loss (Eon + Eoff) by 30% (according to Toshiba's comparative test).

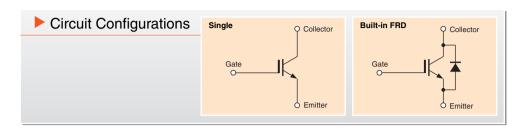


(Vce: 50 V/div, Ic: 5 A/div, Vge: 10 V/div, Loss: 0.2 mJ/div, t: 0.2 μ s/div)

Reduced switching loss of fast-switching IGBTs in comparison with high ruggedness IGBTs Test condition: IC = 20 A, VGE = 15 V, RG = 33 Ω , Ta = 125°C, with inductive load, Vcc = 300 V



Product List



600-V and 1200-V IGBTs (3rd Generation)

			Absolu	ıte Max	kimum F	Ratings			0: ''	V	CE(sat) Ty	p.	t _f T	yp.	
Main	Features	Part Number	VCES	ı	С	Pc	Package		Circuit Configuration		@lc	@Vge		Load	Remarks
Applications			(V)	DC (A)	Pulsed (A)	Tc = 25°C (W)	rackage	Туре	(*1)	(V)	(A)	(V)	(μs)	(*2)	Hemarko
		GT10Q101	1200	10	20	140	TO-3P(N)	-	•	2.1	10	15	0.16	L	
	တ္	GT10Q301	1200	10	20	140	TO-3P(N)	_	Built-in FRD	2.1	10	15	0.16	L	
	High VcEs (1200V)	GT15Q102	1200	15	30	170	TO-3P(N)	_	•	2.1	15	15	0.16	L	
	igh 120	GT15Q301	1200	15	30	170	TO-3P(N)	_	Built-in FRD	2.1	15	15	0.16	L	
	I	GT25Q102	1200	25	50	200	TO-3P(LH)	-	•	2.1	25	15	0.16	L	
		GT25Q301	1200	25	50	200	TO-3P(LH)	-	Built-in FRD	2.1	25	15	0.16	L	
<u> </u>		GT5J301	600	5	10	28	TO-220NIS	_	Built-in FRD	2.1	5	15	0.15	L	
(UPS/PFC)		GT5J311	600	5	10	45	TO-220SM	SMD	Built-in FRD	2.1	5	15	0.15	L	
J J		GT10J301	600	10	20	90	TO-3P(N)	-	Built-in FRD	2.1	10	15	0.15	L	
		GT10J303	600	10	20	30	TO-220NIS	_	Built-in FRD	2.1	10	15	0.15	L	
Motor driving		GT10J312	600	10	20	60	TO-220SM	SMD	Built-in FRD	2.1	10	15	0.15	L	
o io	High Vces (600V)	GT15J301	600	15	30	35	TO-220NIS	_	Built-in FRD	2.1	15	15	0.15	L	
Mot	4 000 000 000	GT15J311	600	15	30	70	TO-220SM	SMD	Built-in FRD	2.1	15	15	0.15	L	
	High	GT20J101	600	20	40	130	TO-3P(N)	_	•	2.1	20	15	0.15	L	
		GT20J301	600	20	40	130	TO-3P(N)	_	Built-in FRD	2.1	20	15	0.15	L	
		GT30J101	600	30	60	155	TO-3P(N)	_	•	2.1	30	15	0.15	L	
		GT30J301	600	30	60	155	TO-3P(N)	_	Built-in FRD	2.1	30	15	0.15	L	
		GT50J102	600	50	100	200	TO-3P(LH)	_	•	2.1	50	15	0.15	L	
		GT50J301	600	50	100	200	TO-3P(LH)	-	Built-in FRD	2.1	50	15	0.15	L	
Power factor correction	Low-frequency switching	GT30J122	600	30	100	75	TO-3P(N)IS	_	•	2.1	50	15	0.25	R	Partial Switching Converter

600-V Fast-Switching IGBTs (4th Generation)

(FS: Fast Switching)

						Circuit		V	CE(sat) Ty	rp.	t _f T	yp.			
Main	Features	Part Number	VCES		lc	Pc	Package		Configuration		@lc	@VgE		Load	Remarks
Applications			(V)	DC (A)	Pulsed (A)	Tc = 25°C (W)		Туре	(*1)	(V)	(A)	(V)	(μs)	(*2)	
		GT10J321	600	10	20	29	TO-220NIS – I		Built-in FRD	2.0	10	15	0.03	L	
es		GT15J321	600	15	30	30	TO-220NIS - I		Built-in FRD	1.9	15	15	0.03	L	
supplies notor)	D	GT15J331	600	15	30	70	TO-220SM	SMD	Built-in FRD	1.75	15	15	0.10	L	Low Vce(sat)
erter power suppl (UPS/PFC/motor)	switching	GT20J321	600	20	40	45	TO-220NIS	_	Built-in FRD	2.0	20	15	0.04	L	
ower PFC/n	swit	GT30J121	600	30	60	170	TO-3P(N)	_	•	2.0	30	15	0.05	L	
er p	Fast	GT30J126	600	30	60	90	TO-3P(N)IS	_	•	1.95	30	15	0.05	L	Isolation Package
Inverter (UPS	ΙĽ	GT30J324	600	30	60	170	TO-3P(N)	_	Built-in FRD	2.0	30	15	0.05	L	
트		GT50J121	600	50	100	240	TO-3P(LH)	_	•	2.0	50	15	0.05	L	
		GT50J325	600	50	100	240	TO-3P(LH)	_	Built-in FRD	2.0	50	15	0.05	L	

FRD: Fast Recovery Diode

*2 R: Resistive load

L : Inductive load

5-2 Soft-Switching Applications

Static inverters in IH cooktops, IH rice cookers and microwave ovens utilize a soft-switching technique which exhibits low switching loss. Toshiba offers IGBTs suitable for soft-switching applications.

Microwave Ovens IH Cookers





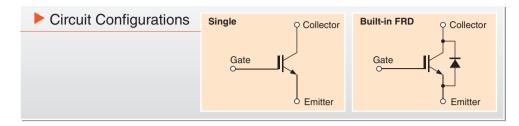






AC Input Voltage	Circuit		IGBT Rating
100 V to 120 V		Waveform	Vces = 900 V to 1000 V Ic = 15 A to 60 A
200 V to 240 V	VCE VCE		Vces = 1200 V to 1500 V Ic = 40 A
100 V to 240 V	Current Resonance	Waveform	VCES = 400 V IC = 40 A to 50 A VCES = 600 V IC = 30 A to 80 A

IH: Induction heating MFP: Multifunction Printer Product List For soft switching



: New product

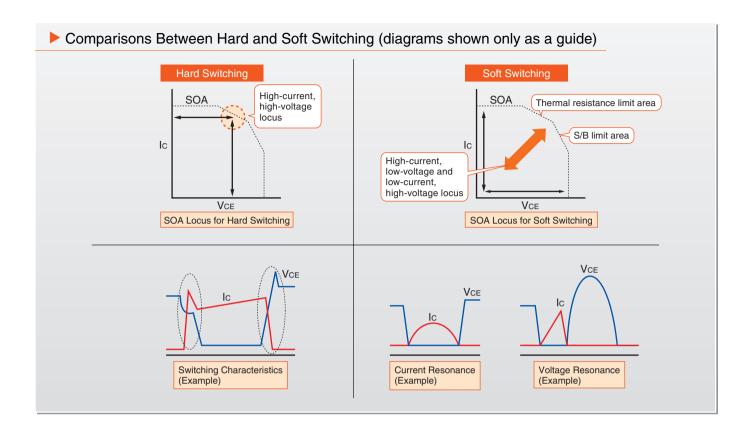
■ IGBTs for Soft-Switching Applications

					Absolu	ıte Maxir	num Ratings	5			Vo	E(sat) Ty	p.	t _f T	yp.	
A	Main pplications	Features	Part Number	VCES (V)	DC (A)	Pulsed (A)	Pc Tc = 25°C (W)	Tj (°C)	Package	Circuit Configuration (*1)	(V)	@Ic (A)	@VgE (V)	(μs)	Load (*2)	Remarks
			GT30J322		30	100	75	150	TO-3P(N)IS		2.1	50	15	0.25		
			GT40J321		40	100	120	150	TO-3P(N)		2.0	40	15	0.11		Fast switching
		•	GT40J322		40	100	120	150	10-3F(N)		1.7	40	15	0.2		
		Current resonance	GT50J322		50	100	130	150	TO-3P(LH)		2.1	50	15	0.25		
	AC 200 V	eson	GT50J322H	600	50	100	130	150	TO OF (ETT)		2.2	50	15	0.11		Fast switching
	AO 200 V	ent r	GT50J327	000	50	100	140	150	TO-3P(N)		1.9	50	15	0.19		
		Curr	GT50J328		50	120	140	150	10 01 (11)		2.0	50	15	0.10		Fast switching
(0			GT60J321		60	120	200	150			1.55	60	15	0.30	2	
ktops			GT60J323		60	120	170	150	TO-3P(LH)		1.9	60	15	0.16		
IH rice cookers and IH cooktops			GT60J323H		60	120	170	150			2.1	60	15	0.12		Fast switching
∐			GT15M321		15	30	55	150	TO-3P(N)IS		1.8	15	15	0.20		
rsar			GT50M322		50	120	156	150	TO-3P(N)	Built-in FRD	2.1	60	15	0.25		
ooke			GT60M303	900	60	120	170	150	TO-3P(LH)		2.1	60	15	0.25		
o eo			GT60M323		60	120	200	150	(=)		2.3	60	15	0.09		Fast switching
王		eou	GT60M324		60	120	254	175			1.7	60	15	0.11		Tj = 175°C
	AC 100 V	Voltage resonance	GT50N321		50	120	156	150	TO-3P(N)		2.5	60	15	0.25		
		e res	GT50N322A		50	120	156	150			2.2	60	15	0.10		Fast switching
		oltag	GT50N324	1000	50	120	150	150			1.9	60	15	0.11		6th generation
		×	GT60N321		60	120	170	150	TO-3P(LH)		2.3	60	15	0.25		
			GT60N322	22	57	120	200	150	. 5 5. (211)		2.4	60	15	0.11		Fast switching
			GT40Q321	1200	42	80	170	150	TO-3P(N)		2.8	40	15	0.41		
	AC 200 V		GT40T321	GT40T321	40	80	230	175	— TO-3P(N)		2.15	40	15	0.24		Tj = 175°C
		GT40T302	1000	40	80	200	150	TO-3P(LH)		3.7	40	15	0.23			

^{*1} FRD: Fast Recovery Diode

^{*2} R : Resistive load

5-2 Soft-Switching Applications



5-3 Strobe Flash Applications

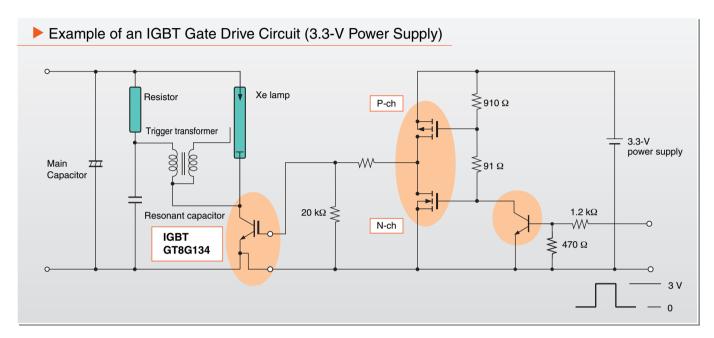


5-3 Strobe Flash Applications

Product List For strobe flashes

2.5-V to 4.0-V Gate Drive Series

The IGBT can operate with a gate drive voltage of 2.5 V to 4.0 V. The common 3.3-V or 5-V internal power supply in a camera can be used as a gate drive power supply to simplify the power supply circuitry. A zener diode is included between the gate and emitter to provide ESD surge protection.



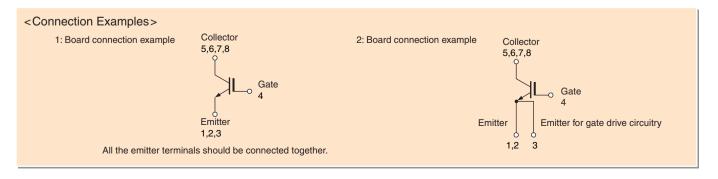
3.3-V Power Supply

Part Number	Vces / Ic	Gate Drive	Vce(s	at) (V)	Pc (W)	Pookogo	Board	Remarks	
Fait Number	VCES/ IC	Voltage Min (V)	Тур.	Vge / Ic	@Ta = 25°C	Package	Connection	Hemarks	
GT5G133	400 V / 130 A	2.5	3.0	2.5 V / 130 A	0.83	TSON-8	1	7th generation	
GT8G136	400 V / 150 A	3	3.5	3 V / 150 A	1.1	TSSOP-8	2	5th generation	
GT8G134	400 V / 150 A	2.5	3.4	2.5 V / 150 A	1.1	TSSOP-8	2	6th generation	

: New product

5-V Power Supply

Part Number	Vces / Ic	Gate Drive Voltage Min	Vce(sat) (V	/)	Pc (W)	Package	Board	Remarks
Fait Number	VCES / IC	(V)	Тур.	V _{GE} / I _C @Ta = 25°C		rackage	Connection	nemarks
GT8G132	400 V / 150 A	4.0	2.3	4.0 V / 150 A	1.1	SOP-8	1	5th generation
GT8G133	400 V / 150 A	4.0	2.9	4.0 V / 150 A	1.1	TSSOP-8	1	5th generation
GT10G131	400 V / 200 A	4.0	2.3	4.0 V / 200 A	1.9	SOP-8	1	5th generation



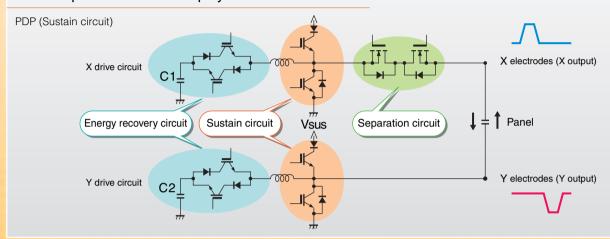
5-4 Plasma Display Panel Applications

Plasma Displays

Parallel MOSFETs have been used for the drive circuitry of plasma display panels (PDPs). Recently, however, IGBTs are commonly used in large current applications due to their superior current conduction capability.



Example of a Plasma Display Panel Drive Circuit



Product List

For plasma display panels

■ 300-V IGBTs

Part Number	Vces / Icp @3 μs	VcE(sat) (V) Typ. @120 A	Pc (W) @Tc = 25°C	Package	Remarks
GT30F122	300 V / 120 A*	2.4	25	TO-220SIS	5th generation
GT30F123	300 V / 200 A	2.1	25	TO-220SIS	6th generation
GT30F124	300 V / 200 A	2.3	25	TO-220SIS	6th generation
GT30F125	330 V / 200 A	1.9	25	TO-220SIS	6th generation
GT45F122	300 V / 200 A	2.2	25	TO-220SIS	5th generation
GT45F123	300 V / 200 A	1.95	26	TO-220SIS	5th generation
GT45F124	300 V / 200 A	1.7	29	TO-220SIS	5th generation
GT45F125	300 V / 200 A	1.45	29	TO-220SIS	5th generation
GT45F127	300 V / 200 A	1.6	26	TO-220SIS	6th generation
GT45F128	330 V / 200 A	1.45	26	TO-220SIS	6th generation
GT45F131	300 V / 200 A	1.7	160	TO-220SM	5th generation

^{*: @100} μs

400-V IGBTs

Vces / lcp @3 μs

400 V / 120 A

430 V / 200 A

430 V / 200 A

430 V / 200 A

400 V / 200 A

430 V / 200 A

430 V / 200 A

400 V / 200 A

Part Number

GT30G122

GT30G123

GT30G124

GT30G125

GT45G122

GT45G123

GT45G124

GT45G125

GT45G127

GT45G128

GT45G131

Pc (W) @Tc = 25°C VcE(sat) (V) Typ. @120 A Package Remarks TO-220SIS 2.6 25 5th generation **TO-220SIS** 2.2 25 6th generation 2.5 25 **TO-220SIS** 6th generation 2.1 25 **TO-220SIS** 6th generation 2.4 25 **TO-220SIS** 5th generation 2.1 26 **TO-220SIS** 5th generation **TO-220SIS** 19 29 5th generation 1.6 29 **TO-220SIS** 5th generation **TO-220SIS** 6th generation

26

160

TO-220SIS

TO-220SM

: New product

6th generation

5th generation

: New product

600-V IGBTs

Part Number	Vces / Icp @3 μs	VCE(sat) (V) Typ. @120 A	Pc (W) @Ta = 25°C	Package	Remarks
GT30J124	600 V / 200 A	2.4	26	TO-220SIS	5th generation

1.55

1.9

: New product

^{*: @100} µs

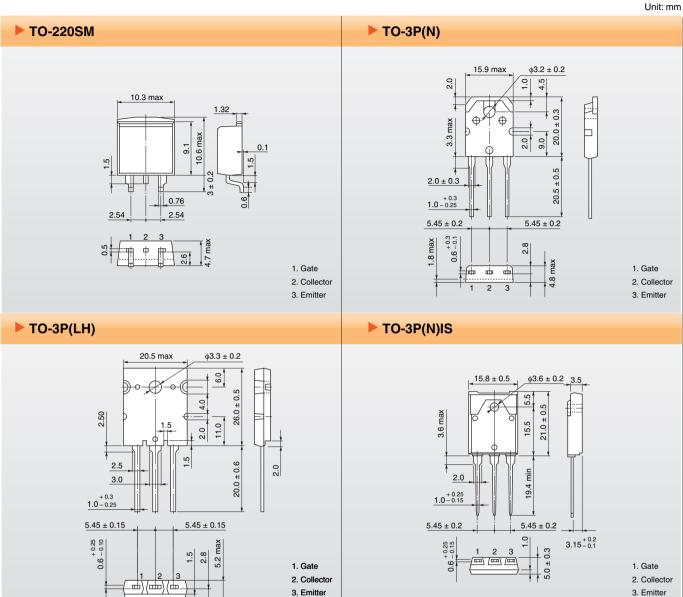
2. Collector

3. Emitter

1 2 3

2. Collector

3. Emitter



Final-Phase and Obsolete Products

The following products are in stock but are being phased out of production. The recommended replacements that continue to be available are listed in the right-hand column. However, the characteristics of the recommended replacements may not be exactly the same as those of the final-phase and obsolete products. Before using a recommended replacement, be sure to check that it is suitable for use under the intended operating conditions.

	Final-Phase or	Absolute Max	imum Ratings		Recommended	Absolute Max	imum Ratings	
Application	Obsolete Product	VCES (V)	Ic (A) DC	Package	Obsolete Replacements	VCES (V)	Ic (A) DC	Package
	MG30T1AL1	1500	30	IH	_	-	-	_
	MG60M1AL1	900	60	IH	GT60M303	900	60	TO-3P(LH)
	GT40M101	900	40	TO-3P(N)IS	_	-	-	_
	GT40M301	900	40	TO-3P(LH)	GT60M303	900	60	TO-3P(LH)
	GT40Q322	1200	39	TO-3P(N)	GT40Q321	1200	42	TO-3P(N)
	GT40Q323	1200	39	TO-3P(N)	GT40Q321	1200	42	TO-3P(N)
	GT40T101	1500	40	TO-3P(LH)	_	_	-	-
	GT40T301	1500	40	TO-3P(LH)	GT40T302	1500	40	TO-3P(LH)
	GT50L101	800	50	TO-3P(L)	GT60M303	900	60	TO-3P(LH)
	GT50M101	900	50	TO-3P(L)	GT60M303	900	60	TO-3P(LH)
	GT50Q101	1200	50	IH	_	-	-	_
	GT50S101	1400	50	IH	_	_	_	
Soft switching	GT50T101	1500	50	IH.			-	
Resonant switching	GT60J101	600	60	TO-3P(L)	GT80J101B	600	60	TO-3P(LH)
-	GT60J322	600	60	TO-3P(LH)	GT60J321	600	60	TO-3P(LH)
-	GT60M101	900	60	TO-3P(L)	GT60M303	900	60	TO-3P(LH)
-	GT60M102	900	60	TO-3P(L)	GT60M303	900	60	TO-3P(LH)
	GT60M103	900	60	TO-3P(L)	GT60M303	900	60	TO-3P(LH)
	GT60M104	900	60 60	TO-3P(L) TO-3P(L)	GT60M303	900	60	TO-3P(LH)
	GT60M105	900	60	TO-3P(LH)	GT60M303	900	60	TO-3P(LH) TO-3P(LH)
	GT60M301 GT60M302	900	60	TO-3P(LH)	GT60M303 GT60M303	900	60	TO-3P(LH)
	GT60M305	900	60	TO-3P(LH)	GT60M303	900	60	TO-3P(LH)
	GT60M303	950	60	TO-3P(LH)	GT60N321	1000	60	TO-3P(LH)
	GT60N323	1050	60	TO-3P(LH)	GT60N321	1000	57	TO-3P(LH)
	GT80J101	600	80	TO-3P(L)	GT80J101B	600	80	TO-3P(LH)
	GT80J101A	600	80	TO-3P(LH)	GT80J101B	600	80	TO-3P(LH)
	GT8J101	600	8	TO-220NIS	GT10J303	600	10	TO-220NIS
	GT8J102	600	8	TO-220SM	GT10J312	600	10	TO-220SM
	GT8N101	1000	8	TO-3P(N)	GT100012	1200	10	TO-3P(N)
	GT8Q101	1200	8	TO-3P(N)	GT10Q101	1200	10	TO-3P(N)
	GT8Q102	1200	8	TO-220SM	_	_	-	_ ` ′
	GT10Q311	1200	10	TO-3P(SM)	_	_	_	_
	GT15J101	600	15	TO-3P(N)	GT20J101	600	20	TO-3P(N)
General-purpose	GT15J102	600	15	TO-220NIS	GT15J301	600	15	TO-220NIS
motors	GT15J103	600	15	TO-220SM	GT15J311	600	15	TO-220SM
General-purpose	GT15N101	1000	15	TO-3P(N)	GT15Q102	1200	15	TO-3P(N)
inverters	GT15Q101	1200	15	TO-3P(N)	GT15Q102	1200	15	TO-3P(N)
liveiteis	GT15Q311	1200	15	TO-3P(SM)	_	-	-	-
	GT20J311	600	20	TO-3P(SM)	-	-	-	_
	GT25H101	500	25	TO-3P(N)	GT30J121	600	30	TO-3P(N)
	GT25J101	600	25	TO-3P(N)	GT30J121	600	30	TO-3P(N)
	GT25J102	600	25	TO-3P(N)IS	GT30J126	600	30	TO-3P(N)
	GT25Q101	1200	25	TO-3P(LH)	GT25Q102	1200	25	TO-3P(LH)
	GT30J311	600	30	TO-3P(SM)	OTF0 1404	-	-	- TO 2D(111)
	GT50J101	600	50 130 (pulsed)	TO-3P(L)	GT50J121	600	50	TO-3P(LH)
-	GT5G101	400	130 (pulsed)	DP		_	_	
	GT5G102	400	130 (pulsed)	DP	-	_	_	
	GT5G103 GT8G101	400	130 (pulsed)	NPM		_	_	
	GT8G101	400	150 (pulsed)	NPM		_	_	
	GT8G102	400	150 (pulsed)	DP		_	_	
	GT8G103	400	150 (pulsed)	DP		_	_	
	GT10G101	400	130 (pulsed)	TO-220NIS	_	_	_	_
Strobe flashes	GT10G101	400	130 (pulsed)	TO-220NIS	_	_	_	_
	GT15G101	400	170 (pulsed)	TO-220NIS	_	_	_	_
	GT20G101	400	130 (pulsed)	TO-220FL	_	_	_	-
	GT20G102	400	130 (pulsed)	TO-220FL	_	_	_	_
	GT25G101	400	170 (pulsed)	TO-220FL	_	_	_	_
	GT25G102	400	150 (pulsed)	TO-220FL	_	_	_	_
	GT50G101	400	100 (pulsed)	TO-3P(N)	_	_	-	_
	GT50G102	400	100 (pulsed)	TO-3P(N)	_	_	-	_
	GT75G101	400	150 (pulsed)	TO-3P(N)	_	-	-	-
Audio amps	GT20D101	250	20	TO-3P(L)	_	_	-	_
	GT20D201	-250	-20	TO-3P(L)	_	_	_	_

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2010-3

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